

What is claimed is:

1. An electronic device comprising:

a semiconductor substrate in which an integrated circuit is formed;

5 an insulating layer which is formed on the semiconductor substrate and includes
an elastically deformable section;

an electrode which is electrically connected with inside of the semiconductor
substrate and is formed on the elastically deformable section; and

10 a substrate on which an interconnect pattern is formed, the interconnect pattern
facing the electrode and being electrically connected with the electrode,

wherein the elastically deformable section is elastically deformed in a manner to
be depressed under the electrode, and presses the electrode against the interconnect
pattern due to elasticity.

15 2. The electronic device as defined in claim 1, further comprising a bump
formed between the electrode and the interconnect pattern, the electrode being
electrically connected with the interconnect pattern through the bump.

20 3. The electronic device as defined in claim 2, wherein the bump includes a
nickel layer.

4. An electronic instrument comprising the electronic device as defined in claim
1.

25 5. A method of manufacturing an electronic device, comprising:
mounting a semiconductor device on a substrate on which an interconnect
pattern is formed,

wherein the semiconductor device includes a semiconductor substrate in which an integrated circuit is formed, an insulating layer which is formed on the semiconductor substrate and includes an elastically deformable section, and an electrode which is electrically connected with inside of the semiconductor substrate and is formed
5 on the elastically deformable section, and

wherein, in the mounting step, the semiconductor device and the substrate are disposed so that the electrode faces the interconnect pattern, and the elastically deformable section is elastically deformed in a manner to be depressed under the electrode.

10

6. The method of manufacturing an electronic device as defined in claim 5,

wherein the semiconductor device further includes a bump formed on the electrode, and

wherein the elastically deformable section is elastically deformed through the
15 bump.